

BFQ18A NPN 4 GHz wideband transistor Rev. 03 – 28 September 2007

**Product data sheet** 

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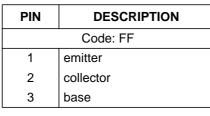
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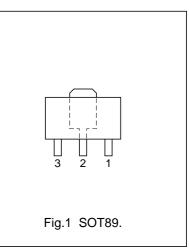


# BFQ18A

### DESCRIPTION

NPN transistor in a plastic SOT89 envelope intended for application in thick and thin-film circuits. It is primarily intended for MATV purposes.





#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS		MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	25	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	18	V
I <sub>C</sub>	DC collector current		_	150	mA
P <sub>tot</sub>	total power dissipation	up to $T_s = 155 \ ^{\circ}C$ (note 1)	-	1	W
f <sub>T</sub>	transition frequency	$I_{C}$ = 100 mA; $V_{CE}$ = 10 V; f = 500 MHz; T <sub>j</sub> = 25 °C	4	-	GHz
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = 0; V <sub>CE</sub> = 10 V; f = 10.7 MHz	1.2	-	pF
d <sub>im</sub>	intermodulation distortion	$\label{eq:lc} \begin{array}{l} I_{C} = 80 \text{ mA}; \ V_{CE} = 10 \ \text{V}; \ \text{R}_{L} = 75 \ \Omega; \\ V_{o} = 700 \ \text{mV}; \ \text{measured at} \\ f_{(p+q-r)} = 793.25 \ \text{MHz} \end{array}$	_	-60	dB

### LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS		MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	25	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	18	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	2	V
I <sub>C</sub>	DC collector current		-	150	mA
P <sub>tot</sub>	total power dissipation	up to $T_s = 155 \text{ °C}$ (note 1)	-	1	W
T <sub>stg</sub>	storage temperature		-65	150	°C
Tj	junction temperature		-	175	°C

### Note

1.  $T_s$  is the temperature at the soldering point of the collector tab.

#### THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE
	thermal resistance from junction to soldering point	up to $T_s = 155 \ ^\circ C$ (note 1)	20 K/W

#### Note

1.  $T_s$  is the temperature at the soldering point of the collector tab.

#### CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$  unless otherwise specified.

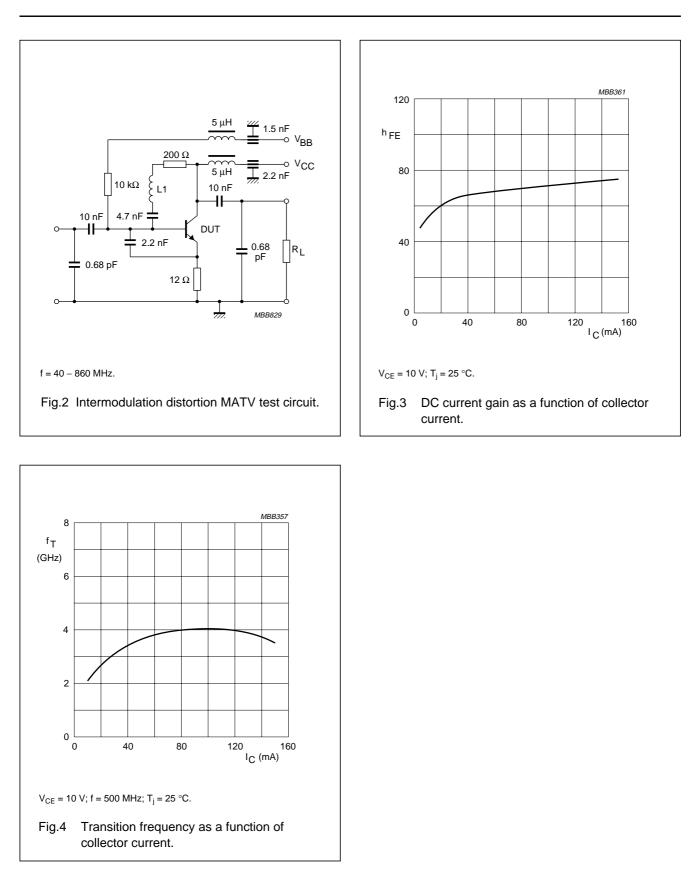
SYMBOL	PARAMETER	PARAMETER CONDITIONS		TYP.	UNIT
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 100 mA; V <sub>CE</sub> = 10 V	25	-	
Cc	collector capacitance	$I_E = i_e = 0; V_{CB} = 10 V; f = 1 MHz$	-	2	pF
Ce	emitter capacitance	$I_{C} = i_{c} = 0; V_{EB} = 0.5 V; f = 1 MHz$	-	11	pF
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = 0; V <sub>CE</sub> = 10 V; f = 10.7 MHz	-	1.2	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 100 mA; V <sub>CE</sub> = 10 V; f = 500 MHz	-	4	GHz
d <sub>im</sub>	intermodulation distortion (see Fig.2)	note 1	-	-60	dB

#### Note

 $\begin{array}{ll} 1. & I_c = 80 \text{ mA}; \ V_{CE} = 10 \ V; \ R_L = 75 \ \Omega; \\ V_p = V_o = 700 \ mV; \ f_p = 795.25 \ MHz; \\ V_q = V_o - 6 \ dB; \ f_q = 803.25 \ MHz; \\ V_r = V_o - 6 \ dB; \ f_r = 805.25 \ MHz; \\ measured \ at \ f_{(p+q-r)} = 793.25 \ MHz. \end{array}$ 

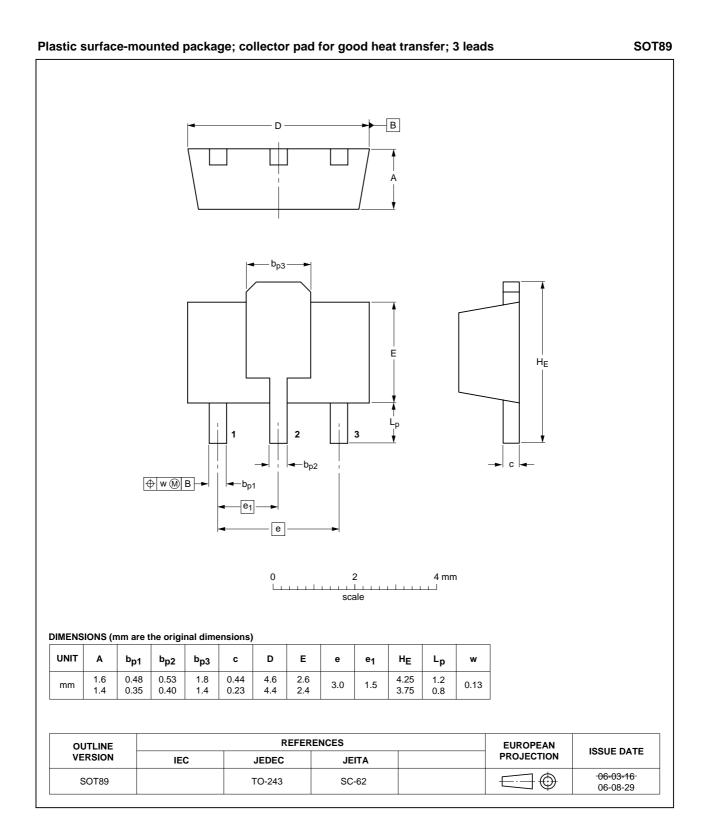
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# BFQ18A



## BFQ18A

#### PACKAGE OUTLINE



## Legal information

### Data sheet status

Document status[1][2]	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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# **Revision history**

Revision history				
Document ID	Release date	Data sheet status	Change notice	Supersedes
BFQ18A_N_3	20070928	Product data sheet	-	BFQ18A_CNV_2
Modifications:	<ul> <li>Fig. 1 and p</li> </ul>	ackage outline updated		
BFQ18A_CNV_2	19950901	Product specification	-	-

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